SHEET 1 OF 2

5	U.S. DEPARTMENT OF COMMERCE			ATTY DOCKET NO.		SERIAL NO.	
Form PTO 1449 U.S. DEPARTMENT OF COMMERCE (Modified) PATENT AND TRADEMARK OFFICE		243028US0DIV		NEW APPLICATION			
			APPLICANT				
LIST OF REFERENCES CITED BY APPLICANT			Toshimitsu TETSUI, et al.				
				FILING DATE		GROUP	
				HEREWITH		1742	
				U.S. PATENT DOCUMENTS		•	
EXAMINER		DOCUMENT	5475	NAME	CLASS	SUB	FILING DATE
INITIAL		NUMBER	DATE	NAME		CLASS	IF APPROPRIATE
XM	AA	5,226,985	07-13-93	Y-W. KIM et al.		 	
Im	AB	5,558,729	09-24-96	Y-W. KIM, et al.			
Xm	AC	5,442,847	08-22-95	S.L. SEMIATIN, et al.			
Im	AD	5,846,351	12-08-98	N. MASAHASHI, et al.			
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		DOCUMENT NUMBER	DATE	COUNTRY		YES	TRANSLATION S NO
m	AO	64-042539	02-14-89	JAPAN			X
Im	ΑP	1-298127	12-01-89	JAPAN			X
MM	AQ	6-049565	02-22-94	JAPAN			X
m	AR	6-041661	02-15-94	JAPAN		<u> </u>	X
-	AS-	62-000215	01-06-87	JAPAN			X
Son	AT	4-066630	03-03-92	JAPAN			X
Xm	AU	4-124236	04-24-92	JAPAN		<u> </u>	x
Em	AV	6-49624	02-22-94	JAPAN			X
3,,		OTHER RI	FERENCES	(Including Author, Title, Date, Pertinen	t Pages, e	etc.)	
	г						of Controlled
Sm	AW	D. ZHANG et al., Intermetallics, Vol. 7, No. 10, XP-004177382, pps. 1081-1087, "Characterization of Controlled Microstructures in A TIAI (Cr, Mo, Si, B) ALLOY," October 1999.					
m	AX	*ASM Handbook: Vol. 3 Alloy Phase Diagrams," ASM International, 1992, p. 254.					
	AY					_	
	AZ				☐ Ado	litional Refe	erences sheet(s) attached
Examiner	-/	for m	1		<u></u>	nsidered	10/12/05
*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							

SHEET 2 OF 2

Form PTO 1449		U.S. DEPARTMENT	OF COMMERCE	ATTY DOCKET NO. 243028US0DIV		SERIAL NO.		
(Modified)		PATENT AND TRAI	DEMARK OFFICE			NEW APPLICATION		
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LIST OF REFERENCES CITED BY APPLICANT				Toshimitsu TETSUI, et al.				
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				HEREWITH		1742		
	U.S. PATENT DOCUMENTS							
EXAMINER		DOCUMENT				SUB	FILING DATE	
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			F0	REIGN PATENT DOCUMENTS				
		DOCUMENT	DATE	COUNTRY	TRANSLATION			
		NUMBER				YES	NO	
Sm	AO	WO 96/30551	10-03-96	WIPO				
Sm.	AP	1-259139	10-16-89	JAPAN			X	
Jun	AQ	43 18 424	12-08-94	GERMANY			X	
ym	AR	6-340955	12-13-94	JAPAN			×	
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	AU							
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		OTHER RE	FERENCES (Including Author, Title, Date, Pertinen	t Pages, e	tc.)		
								
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	AZ				Addi 🗌	tional Refe	rences sheet(s) attached	
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	Examiner Date Considered 10/12/05							
*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.								



LIST OF RELATED CASES

Docket Number	Serial or Patent Number	Filing or <u>Issue Date</u>	Inventor/ Applicant
 230230US0	10/286,854	11/04/02	TETSUI
 _24 3028US 0 DIV*	10/667,651	09/23/03	TETSUI, et al.

The serial numbers above have been considered by the examiner but are crossed out as they will not be printed in the references cited section.

Jun pu 10/12/05

^{*}Present Application; listed for information NFO/tas